



U.S. Ser. No. 10/043,896  
Our File: MIT 10523

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**APPLICANT:** Lee et al. **GROUP:** 2871  
**SERIAL NO:** 10/043,896 **EXAMINER:** G.Y. Wang  
**FILED:** January 9, 2002  
**FOR:** HIGH DENSITY INTEGRATED OPTICAL CHIP

**Commissioner of Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**Sir:**

**AMENDMENT**

In response to the Office Action mailed June 7, 2005, please amend the above-identified application as follows: